Docket No.:

YHK-0155

## **DECLARATION AND POWER OF ATTORNEY**

-		
As a below named inventor, I here	by declare that:	
My residence, post office and citize	enship are as stated below next to my na	ime,
inventor (if plural names are listed	d below) of the subject matter claimed	isted below) or an original, first and joint and for which a patent is sought on the LAY PANEL USING THE SAME,
is attached hereto	as filed on <u>January 25, 2006</u> as Applica	tion Serial No. <u>10/565,809</u> and was
amended on	(if applicable)	
I hereby state that I have reviewed claims, as amended by any amendr		pove identified specification, including the
I acknowledge the duty to disclose with Title 37, Code of Federal Reg		be material to patentability in accordance
or inventor's certificate, or 365(a) than the United States of America	of any PCT international application was, listed below and have also identified sertificate, or of any PCT internation	(b) of any foreign application(s) for patent hich designated at least one country other below, by checking the box, any foreign nal application having a filing date before
Prior Foreign Application(s): Number	Country	Foreign Filing Date <u>Month/Day/Year</u>
10-2003-0051306	Korea	July 25, 2003
I hereby claim the benefit under 3	5 U.S.C. 119(e) of any United States pro	visional application(s) listed below.
Application Number(s):	Filing Date (M	Month/Day/Year)
I hereby claim the benefit under		
each of the claims of this applicat the manner provided by the first p is material to patentability as defi	ng the United States of America, listed l ion is not disclosed in the prior United paragraph of 35 U.S.C. 112, I acknowled	below and, insofar as the subject matter of States or PCT international application in Ige the duty to disclose information which illable between the filing date of the prior
each of the claims of this applicat the manner provided by the first p is material to patentability as defi	ng the United States of America, listed I ion is not disclosed in the prior United paragraph of 35 U.S.C. 112, I acknowled ned in 37 CFR 1.56 which became ava	below and, insofar as the subject matter of States or PCT international application in Ige the duty to disclose information which illable between the filing date of the prior
each of the claims of this applicat the manner provided by the first p is material to patentability as defi application and the national or PC Prior U. S. Application	ng the United States of America, listed bein is not disclosed in the prior United paragraph of 35 U.S.C. 112, I acknowled ned in 37 CFR 1.56 which became awa'T international filing date of this applications.	below and, insofar as the subject matter of States or PCT international application in alge the duty to disclose information which ulable between the filing date of the prior ation.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the attorney(s) and/or agent(s) associated with Customer Number 34610 to prosecute this application and transact all business in the Patent and Trademark Office.

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